

SIGNAL TRANSMISSION PLATE USED IN AN ASSEMBLY PACKAGE

ABSTRACT OF THE DISCLOSURE

A signal transmission plate used in an assembly package includes at least one insulating layer, at least one layout wire layer formed on the insulating layer, and a solder mask layer formed on the layout wire layer. The solder mask layer exposes partial area of the layout wire layer at the center and peripheries of the signal transmission plate to form a plurality of die bonding pads and a plurality of wire bonding pads.